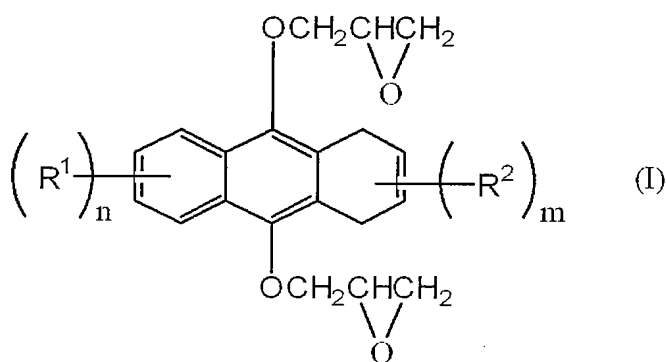


I. LISTING OF CLAIMS:

The following claims will replace all prior versions of claims in the present application.

Listing of Claims:

1. (Previously Presented) A sealant epoxy-resin molding material, comprising an epoxy resin (A) and a hardening agent (B), wherein the epoxy resin (A) contains a compound represented by the following General Formula (I):



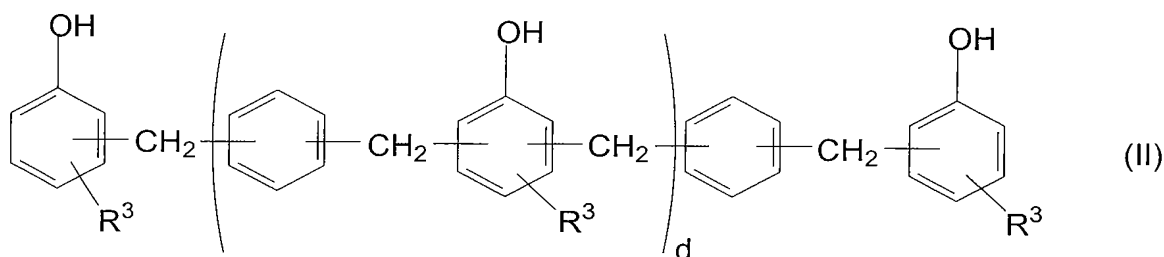
wherein in General Formula (I), R^1 represents a group selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms, and the groups R^1 may be the same as, or different from, each other;

n is an integer of 0 to 4;

R^2 represents a group selected from substituted or unsubstituted hydrocarbon groups having 1 to 12 carbon atoms and substituted or unsubstituted alkoxy groups having 1 to 12 carbon atoms, and the groups R^2 may be the same as, or different from, each other; and

m is an integer of 0 to 6.

2. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, wherein the hardening agent (B) contains a compound represented by the following General Formula (II):



wherein R^3 represents a group selected from a hydrogen atom and substituted or unsubstituted monovalent hydrocarbon groups having 1 to 10 carbon atoms; and
 d is an integer of 0 to 10.

3. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising a hardening accelerator (C).

4. (Original) The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is triphenylphosphine.

5. (Original) The sealant epoxy-resin molding material according to Claim 3, wherein the hardening accelerator (C) is an adduct of a tertiary phosphine compound and a quinone compound.

6. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising an inorganic filler (D).

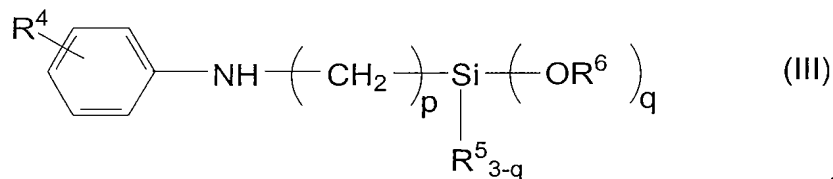
7. (Original) The sealant epoxy-resin molding material according to Claim 6, wherein the content of the inorganic filler (D) is 60 to 95 wt % with respect to the sealant epoxy-resin molding material.

8. (Previously Presented) The sealant epoxy-resin molding material according to Claim 6, wherein the content of the inorganic filler (D) is 70 to 90 wt % with respect to the sealant epoxy-resin molding material.

9. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising a coupling agent (E).

10. (Original) The sealant epoxy-resin molding material according to Claim 9, wherein the coupling agent (E) contains a secondary amino group-containing silane-coupling agent.

11. (Previously Presented) The sealant epoxy-resin molding material according to Claim 10, wherein the secondary amino group-containing silane-coupling agent contains a compound represented by the following General Formula (III):



wherein R^4 represents a group selected from a hydrogen atom, alkyl groups having 1 to 6 carbon atoms, and alkoxy group having 1 to 2 carbon atoms;

R^5 represents a group selected from alkyl groups having 1 to 6 carbon atoms and a phenyl group;

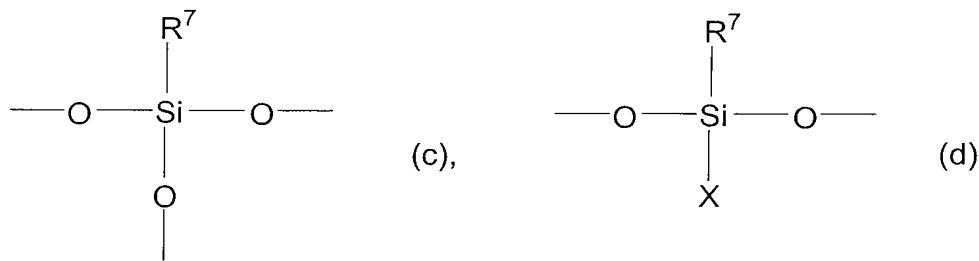
R^6 represents a methyl or ethyl group;

p is an integer of 1 to 6; and

q is an integer of 1 to 3.

12. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

13. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d),



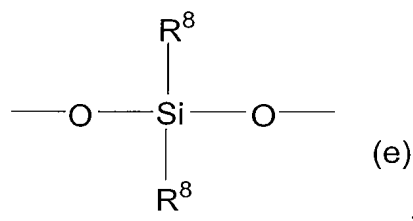
a terminal selected from R^7 , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000,

wherein R^7 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms;

the groups R^7 in the silicon-containing polymer may be the same as, or different from, each other; and

X represents an epoxy group-containing monovalent organic group.

14. (Previously Presented) The sealant epoxy-resin molding material according to Claim 13, wherein the silicon-containing polymer (F) has the following bond (e) additionally:



wherein R^8 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms; and

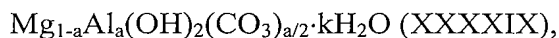
the groups R^8 in the silicon-containing polymer may be the same, as or different from, each other.

15. (Previously Presented) The sealant epoxy-resin molding material according to Claim 13, wherein the softening temperature of the silicon-containing polymer (F) is 40°C or higher and 120°C or lower.

16. (Previously Presented) The sealant epoxy-resin molding material according to Claim 13, wherein R^7 in the silicon-containing polymer (F) is at least one of a substituted or unsubstituted phenyl group and a substituted or unsubstituted methyl group.

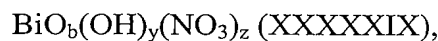
17. (Previously Presented) The sealant epoxy-resin molding material according to Claim 13, wherein the rate of substituted or unsubstituted phenyl groups having 1 to 12 carbon atoms in all groups R^7 in the silicon-containing polymer (F) is 60 to 100 mol %.

18. (Previously Presented) The sealant epoxy-resin molding material according to Claim 1, further comprising at least one of a compound (G) represented by Compositional Formula (XXXXIX) and a compound (H) represented by the following Compositional Formula (XXXXIX):



wherein $0 < a \leq 0.5$; and

k is a positive number), and

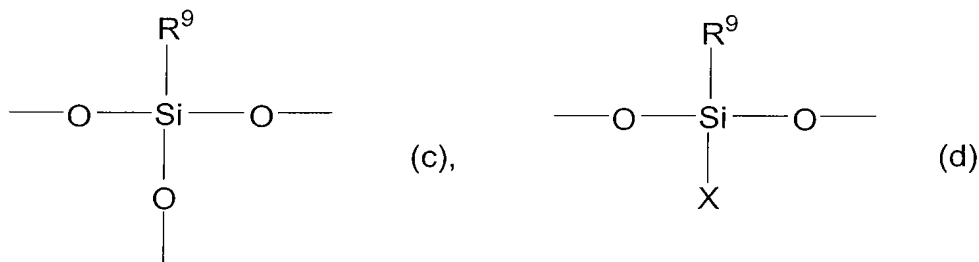


wherein $0.9 \leq b \leq 1.1$, $0.6 \leq y \leq 0.8$, and $0.2 \leq z \leq 0.4$.

19. (Previously Presented) An electronic component device, comprising an element sealed with the sealant epoxy-resin molding material according to Claim 13.

20. (Previously Presented) The sealant epoxy-resin molding material according to Claim 6, further comprising a coupling agent (E).

21. (Previously Presented) The sealant epoxy-resin molding material according to Claim 20, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d),



a terminal selected from R^9 , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000,

wherein R^9 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms;

the groups R^9 in the silicon-containing polymer may be the same as, or different from, each other; and

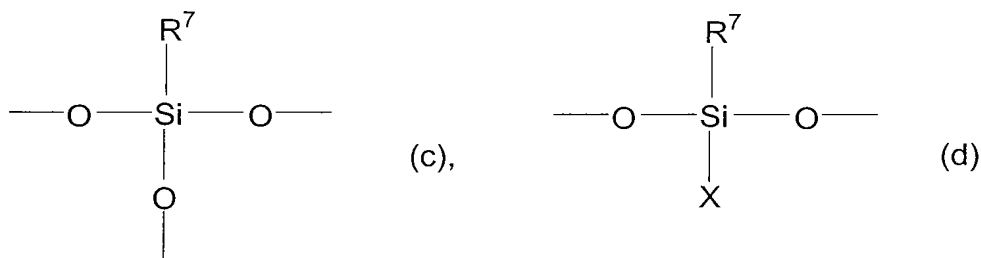
X represents an epoxy group-containing monovalent organic group.

22. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, further comprising an inorganic filler (D).

23. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, further comprising a coupling agent (E).

24. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, wherein the epoxy resin (A) and the hardening agent (B) are melt-mixed previously.

25. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, further comprising a silicon-containing polymer (F) having the following bonds (c) and (d),



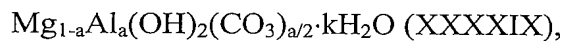
a terminal selected from R^7 , a hydroxyl group and alkoxy groups, and an epoxy equivalence of 500 to 4,000,

wherein R^7 represents a group selected from substituted or unsubstituted monovalent hydrocarbon groups having 1 to 12 carbon atoms;

the groups R^7 in the silicon-containing polymer may be the same as or different from each other; and

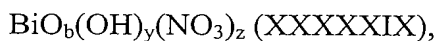
X represents an epoxy group-containing monovalent organic group.

26. (Previously Presented) The sealant epoxy-resin molding material according to Claim 3, further comprising at least one of a compound (G) represented by Compositional Formula (XXXXIX) and a compound (H) represented by the following Compositional Formula (XXXXXXIX):



wherein $0 < a \leq 0.5$; and

m is a positive number), and



wherein $0.9 \leq b \leq 1.1$, $0.6 \leq y \leq 0.8$, and $0.2 \leq z \leq 0.4$.